

U.S.S.N. 09/827,106

In The Claims

Claim 9 has been cancelled without prejudice.

Claim 1 has been amended as follows:

B'  
C 1. (Twice Amended) A matrix form semiconductor package substrate having an electrode situated in-between a plurality of integrated circuit (IC) package substrates for providing electrical communication to conductive pads situated on said <sup>plurality of</sup> IC package substrates comprising:

said plurality of IC package substrates integrally formed on a substrate strip in a matrix form having a boundary between each two of said plurality of IC package substrates, each of said plurality of IC package substrates having a multiplicity of conductive pads; and

said electrode formed in a rectangular-shaped, corrugated configuration along said boundary with each one of two legs of a corrugation connected to only one IC package substrate for providing electrical communication to said multiplicity of conductive pads and for providing insulation between said <sup>package substrates</sup> multiplicity of conductive pads after said plurality of IC ~~packages~~ are cut along said boundary through said electrode.

B

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Claim 11 has been amended as follows:

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B<sup>2</sup>  
11. (Twice Amended) A ball grid array (BGA) package substrate comprising:

an insulating substrate having a top surface;

a plurality of BGA package substrates formed on said top surface of said insulating substrate;

a multiplicity of conductive traces emanating from each one of said plurality of BGA package substrates, each of said multiplicity of conductive traces provides electrical communication between a conductive pad and a wirebond finger situated on said BGA package substrate; and

an electrode having a rectangular-shaped, corrugated configuration with each one of two legs of a corrugation connected to only one <sup>BGA</sup> package substrate.

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REMARKS

Thorough examination and careful review of the application by the Examiner is noted and appreciated.

Claims 1-18 are pending in the application. Claims 1-18 stand rejected.

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